

Embedded MEMS actuators for CNT straining tests

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Abstract

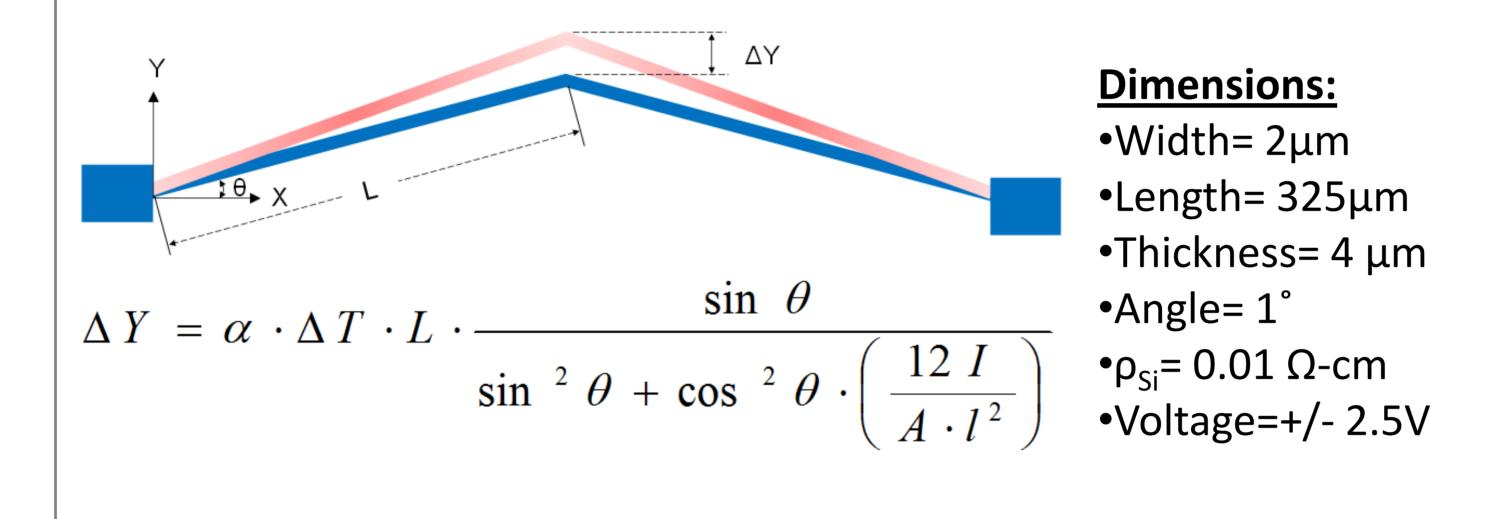
We present an approach for straining CNTs, employing an embedded MEMS actuator, that is different and less disruptive than previous methods, such as ATM indentation. For the first time, we report on the electromechanical response –including tensile loading and transport measurements- of suspended CNTs strained by a MEMS actuator, which is fabricated by an integrated CNT-MEMS process flow.

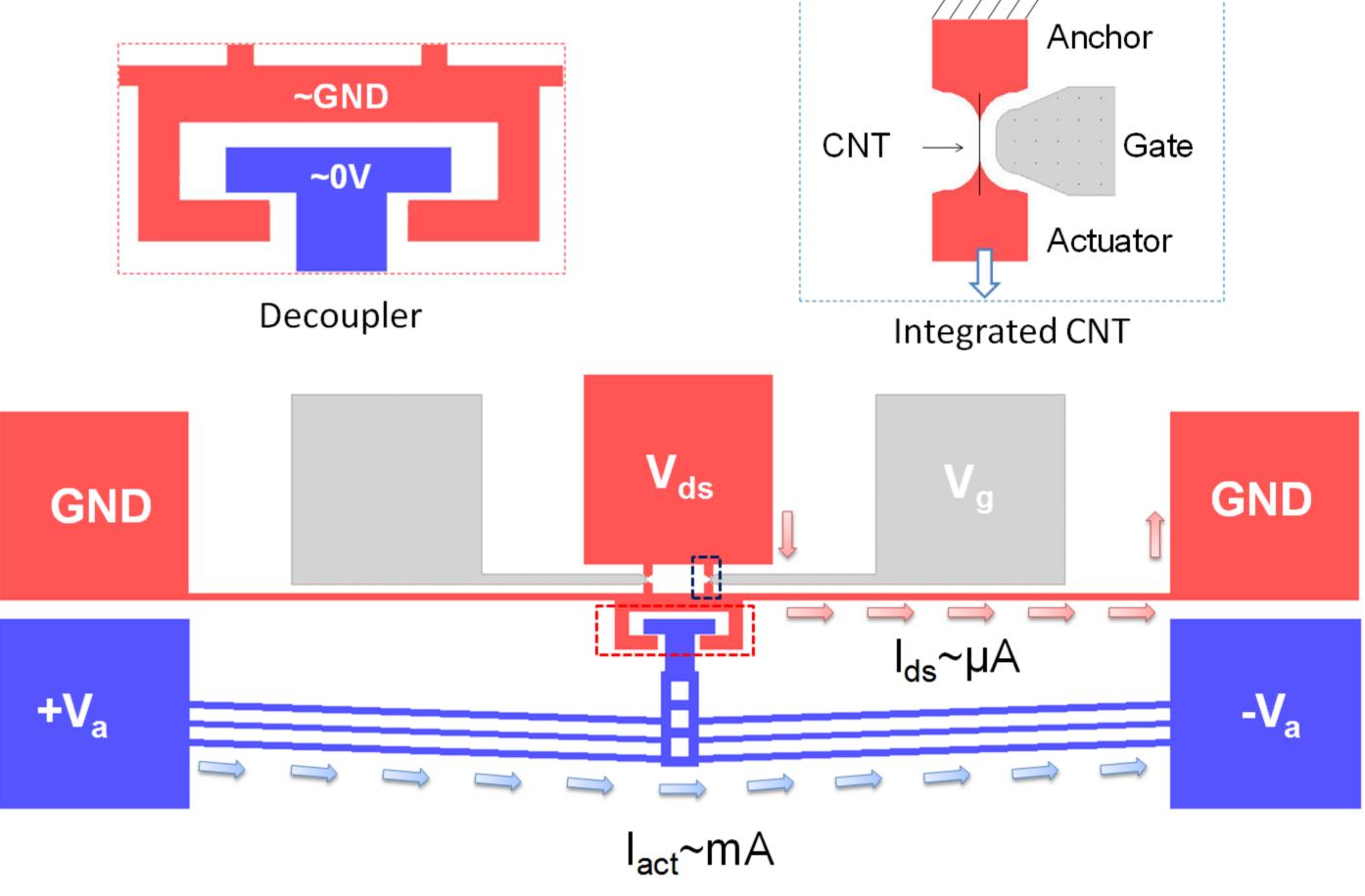
Working mechanism

By our developed integration process [2], a suspended CNT can be integrated onto Si tips, as shown in the figure below. When the displacement of the actuator exceeds the gap in the current-decoupler, the CNT under test is strained.

MEMS actuator design

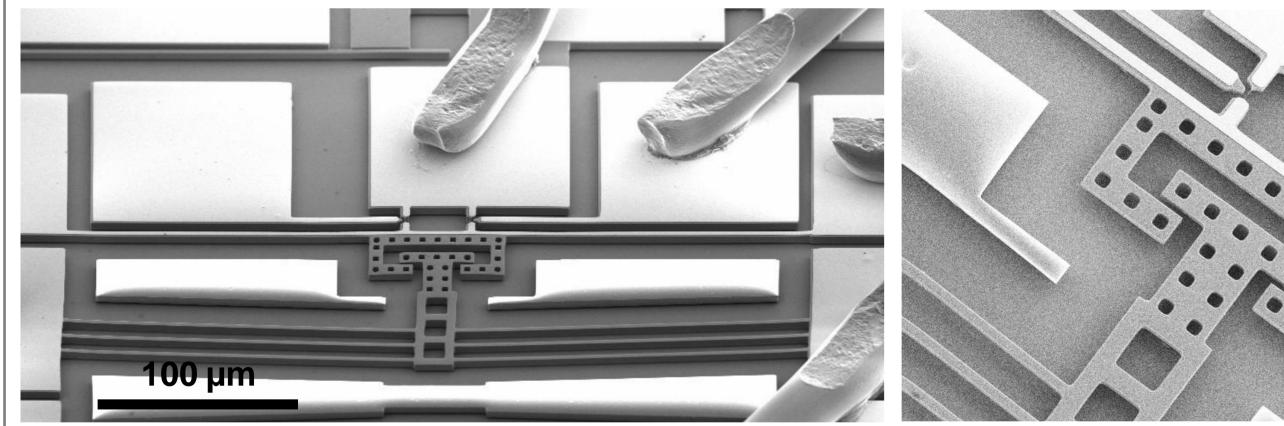
To lower the driving voltage of the strain test, we choose bentbeam electro-thermal actuators. The free-displacement is determined by the dimensions of the beams as well as the temperature difference, as described by the formula below [1].





To measure the current through the CNT (I_{ds}) , a currentdecoupler is designed to insulate I_{ds} from actuator current, I_{act} . By symmetric biasing and the native oxide on the sidewalls of the decoupler, these two currents can be separated.

Fabrication results



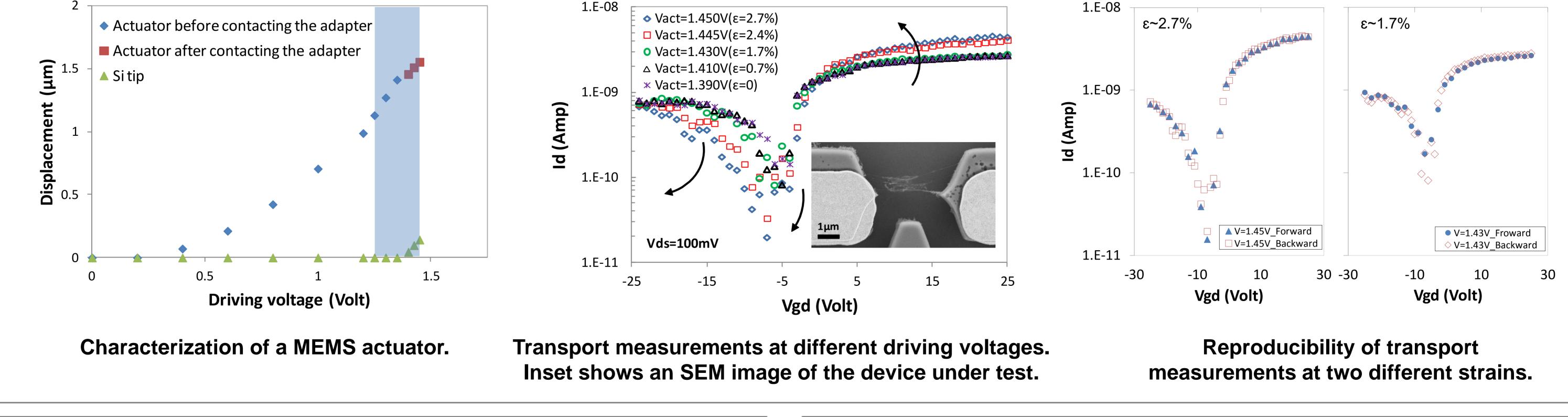
Close-up of the decoupler

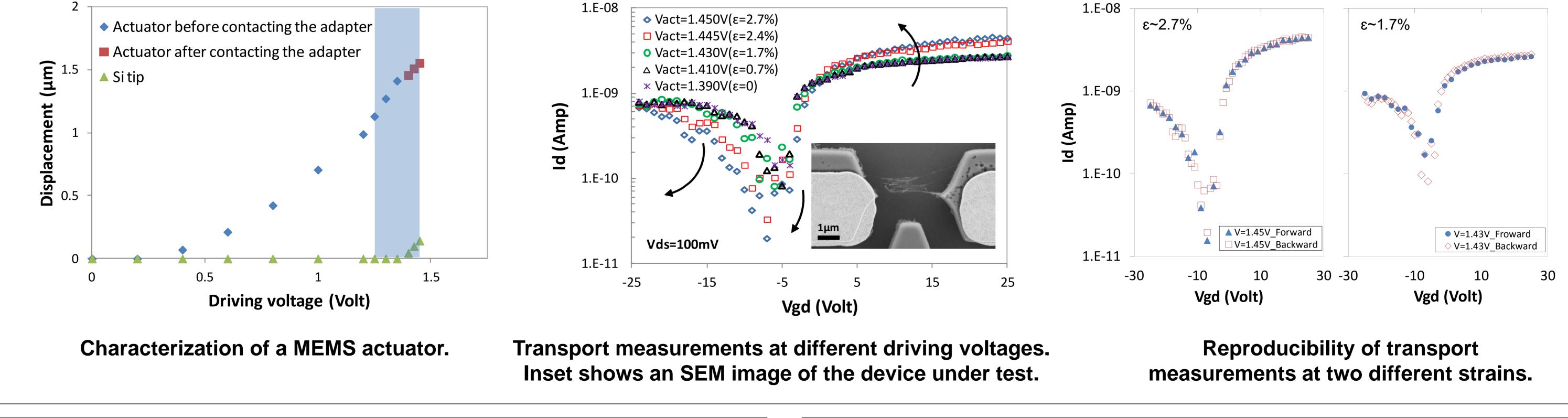
Testing protocol 1st sweep 2nd sweep (Volt) 1.45 .39 oltage $\Delta V_2 = 5 mV$.35 $\Delta V_1 = 20 \text{mV}$ tuat .25 \sim Backward Backward Forward Forward sweep sweep sweep sweep \rightarrow Time

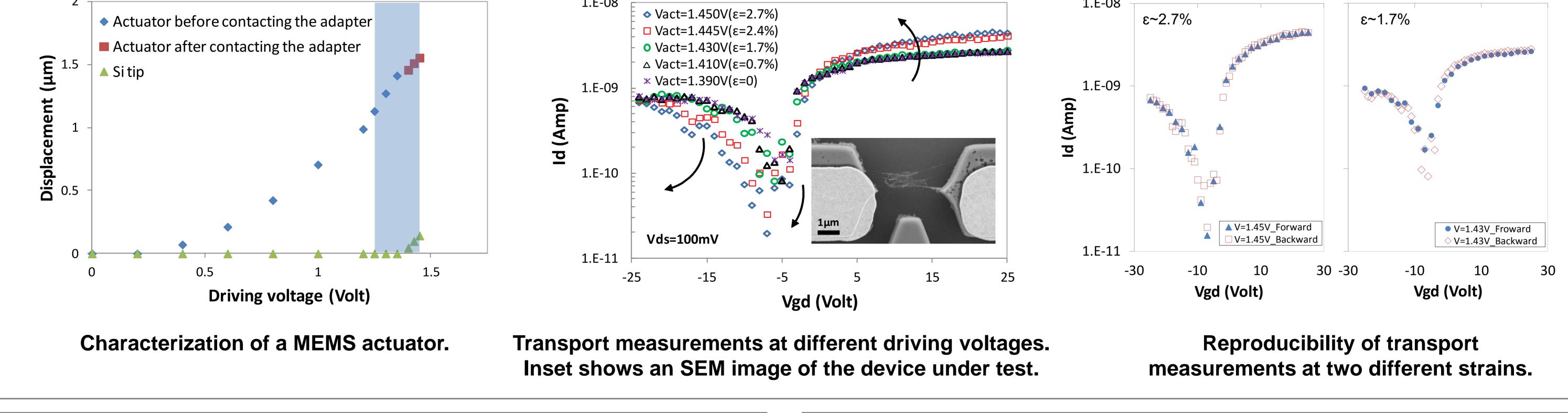
Driving voltage sweep for electro-mechanical characterization

Strain tests of CNTs

SEM tilt view of the device







Acknowledgements

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Reference

[1] Y. Zhu, et al., J. Micromech. Microeng. 16 (2006) 242–253

[2] S.-W. Lee, et al., Proc. IEEE NEMS 2011, pp. 37-40

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